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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: H. NAKAMURA, et al.
Application No.: 10/500,119
Filed: JUNE 25, 2004
For: CONNECTION BOARD, AND MULTI-LAYER WIRING BOARD,
SUBSTRATE FOR SEMICONDUCTOR PACKAGE AND
SEMICONDUCTOR PACKAGE USING CONNECTION BOARD,
AND MANUFACTURING METHOD THEREOF
Group AU: 2841
Examiner: Ishwarbhai B. Patel
Confirm. No.: 7910

**INFORMATION DISCLOSURE STATEMENT
UNDER 37 CFR 1.97 AND 1.98**

Mail Stop: AMEND – NO FEE

Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

April 24, 2008

Sir:

Pursuant to Applicants' duty of disclosure, enclosed please find a copy of an Official Action issued January 25, 2008, in connection with a counterpart Chinese patent application, together with a partial English translation thereof. Also enclosed is a copy of CN1198191A, cited in this Official Action, and a copy of WO 96/33294, which corresponds to CN1198191A. Still further enclosed is (1) an English-language abstract of WO 96/33294, corresponding to CN1198191A, and (2) Form PTO/SB/08A, listing the enclosed documents.

Note the following documents, cited in the enclosed Official Action but not being submitted herewith:

- (1) JP 2001-326458;
- (2) JP 2001-326459;
- (3) JP 2001-15920;
- (4) JP 06-350258;
- (5) JP 2001-36250; and
- (6) JP 2000-286554.

These above-listed documents numbered (1)-(6) have previously been submitted in connection with the above-identified application, with the Information Disclosure Statement submitted June 25, 2004, upon originally filing the above-identified application.

This Information Disclosure Statement is being submitted subsequent to a first Office Action on the merits in the above-identified application, but prior to a Final Office Action or issuance of a Notice of Allowance, or issuance of any other action closing prosecution on the merits in the above-identified application. For satisfying requirements of 37 CFR 1.97(c), the following Statement is made under 37 CFR 1.97(e):

Each item of information contained in this Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement.

To the extent that the enclosed documents are not in English, it is respectfully submitted that requirements of 37 CFR 1.98(a)(3) are satisfied by the enclosed partial English translation of the enclosed Official Action, and/or by the enclosed English-language abstract, and/or by submission of the corresponding published international patent application.

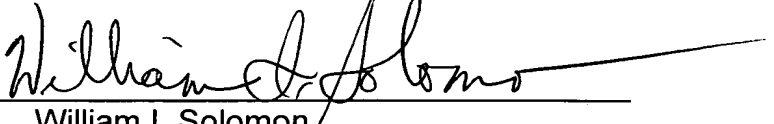
In view of the foregoing, it is respectfully submitted that all applicable requirements of 37 CFR 1.97 and 1.98 have been satisfied, in connection with the presently submitted documents. Accordingly, consideration of the submitted documents, upon further examination of the above-identified application, is respectfully requested.

Please charge any shortage of fees due in connection with the filing of this paper to the Deposit Account of Antonelli, Terry, Stout & Kraus, LLP, Deposit

Account No. 01-2135 (case No. 1204.43988X00), or credit any excess fees paid to
such Deposit Account.

Respectfully submitted,

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